

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
TOSHIYASU ITO	05/19/2020
MASAAKI SAITO	05/19/2020
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State/Country:	JAPAN
Postal Code:	144-8581
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	29729290
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DATE SIGNED:	05/26/2020
Total Attachments: 2	
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Joint

ASSIGNMENT

WHEREAS, we, **Toshiyasu Ito and Masaaki Saito**, have invented a certain improvement in **Connector For Optical Module** described in an application for Patent,

- the specification of which is about to be filed in the United States Patent Office (*use for utility (37 CFR § 1.53(b)) and design filings only*);
- is about to be filed in the United States Patent Office as a Provisional Application;
- the specification of which is United States Application No. **29/729,290**, filed **March 25, 2020**;
- the specification of which is a Patent Cooperation Treaty Application, International Application No. [], filed [], which designates the United States of America [and is assigned United States Application No. []];
- which was patented under United States Patent No. [].

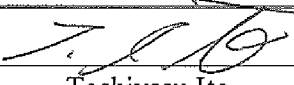
WHEREAS, **YAMAICHI ELECTRONICS CO., LTD.** (hereinafter "ASSIGNEE"), a corporation organized and existing under the laws of **Japan** and having a usual place of business at **2-16-2, Minamikamata, Ota-ku Tokyo 144-8581 Japan** desires to confirm its interest therein in accordance with agreements duly entered into with us;

NOW, THEREFORE, to all whom it may concern be it known that for and in consideration of said agreements and of other good and valuable consideration, the receipt of which is hereby acknowledged, we have sold, assigned and transferred and by these presents do hereby sell, assign and transfer unto said ASSIGNEE, its successors, assigns and legal representatives, the entire right, title and interest in and throughout the United States of America, its territories and all foreign countries, in and to said invention as described in said application, together with the entire right, title and interest in and to said application and such Letters Patent as may issue on said invention; said invention, application and Letters Patent to be held and enjoyed by said ASSIGNEE for its own use and behalf and for its successors, assigns and legal representatives, to the full end of the term for which said Letters Patent may be granted as fully and entirely as the same would have been held by us had this assignment and sale not been made; we hereby convey all rights arising under or pursuant to any and all international agreements, treaties or laws relating to the protection of industrial property by filing any such applications for Letters Patent. We hereby acknowledge that this assignment, being of the entire right, title and interest in and to said invention, carries with it the right in ASSIGNEE to apply for any and all related provisional and nonprovisional, international and national phase applications, including any and all substitution, reissue, divisional, continuation, and continuation-in-part applications, and obtain from competent authorities in all countries of the world any and all Letters Patent by attorneys and agents of ASSIGNEE's selection and the right to procure the grant of all such Letters Patent to ASSIGNEE for its own name as assignee of the entire right, title and interest therein; we hereby expressly authorize the filing of an International Patent Application under the

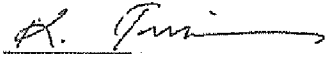
Patent Cooperation Treaty which corresponds to and claims the priority of the above-identified application;

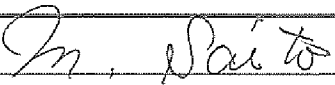
AND, we hereby further agree for ourselves and our executors and administrators to execute upon request any other lawful documents and likewise to perform any other lawful acts which may be deemed necessary to secure fully the aforesaid invention to said ASSIGNEE, its successors, assigns and legal representatives, but at its or their expense and charges, including the execution of applications for patents in foreign countries, and the execution of any future applications including substitution, reissue, divisional or continuation, continuation-in-part applications, and all related provisional and nonprovisional, international and national phase applications, and preliminary or other statements and the giving of testimony in any interference or other proceeding in which said invention or any application or patent directed thereto may be involved;

AND, we do hereby authorize and request each Patent Office and the Commissioner of Patents of the United States to issue such Letters Patent as shall be granted upon said invention to said ASSIGNEE, its successors, assigns, and legal representatives.

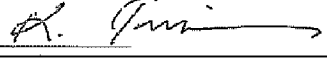
Inventor  Date 19, May 2020
Toshiyasu Ito

Witness Signature 谷岡道修
Print Witness Name Michinobu TANIOKA

Witness Signature 
Print Witness Name Kazuya FUJISAWA

Inventor  Date 19, May, 2020
Masaaki Saito

Witness Signature 谷岡道修
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